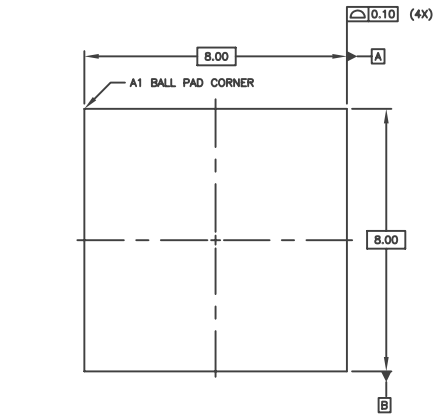
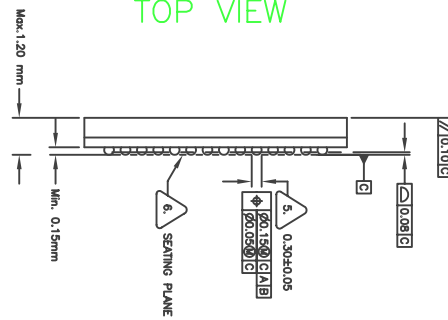


REVISIONS

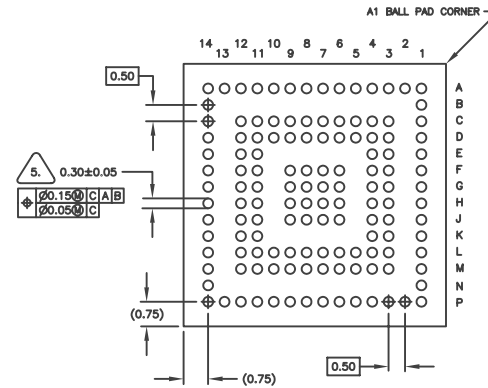
ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
	A		NEW RELEASE	10/12/06	RUTH LIN
	B		Update labeling on overall package height and the collapsed ball height	02/13/07	RUTH LIN
	C		Change to Rev C because of rename from MECH DRAWING to MKT DRAWING	05/15/07	RUTH LIN



TOP VIEW



SIDE VIEW



BOTTOM VIEW

132 SOLDER BALLS

7. REFERENCE SPECIFICATIONS:
 A. AWW SPEC #001-0531-2234: PACKING OPERATION PROCEDURE.
 B. AWW SPEC #001-0519-2062: MARKING.

6. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
 5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.

4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 196.
 3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 14 X 14.
 2. THE BASIC SOLDER BALL GRID PITCH IS 0.50mm.
 1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.

NOTES: UNLESS OTHERWISE SPECIFIED

DRAWN RUTH LIN	DATE 10/12/06	QUICKLOGIC CORP
APPROVED BY K.H. THE	DATE 10/14/06	
TF-BGA, 8x8x1.2mm 2L, PU132 BALL, 0.50mm PITCH		
PROJECTION 	SCALE N/A	DWG NO 03-015-84
REFERENCE PACKAGE OUTLINES	QUICKLOGIC PKG CODE: PU132	REV C
		SHEET 1 OF 1